

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (currently amended) A mold die comprising a first die having a recess ~~in~~ of a predetermined form and a second flat die, ~~said mold die being for disposing~~ said first die to be disposed on a surface of a wiring board which has a plurality of openings and ~~bears a semiconductor chip~~ mounted on said surface via an elastic material, ~~which surface bears said semiconductor chip, and for disposing~~ said second die to be disposed on a back of said surface of said wiring board on which ~~bears~~ said semiconductor chip is mounted, and for sealing with an insulating resin a periphery of said semiconductor chip and at least one of said openings of said wiring board, wherein

said second die comprises a protrusion disposed around an area overlapping said opening to be sealed with said insulating resin.

2. (currently amended) A method for manufacturing a semiconductor device by sealing, by transfer mold processing using a die, a semiconductor chip ~~borne~~ mounted on a wiring board via an elastic material, which board includes an insulating substrate with a plurality of openings thereon on which a conductive pattern is formed, and by sealing at least one of said openings, wherein

a die having a protrusion disposed around an area overlapping said ~~sealed~~ opening to be sealed is used for a back die member to be placed in contact with of the surface of said wiring board on the opposite side on which ~~bears~~ said semiconductor chip is mounted.